

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

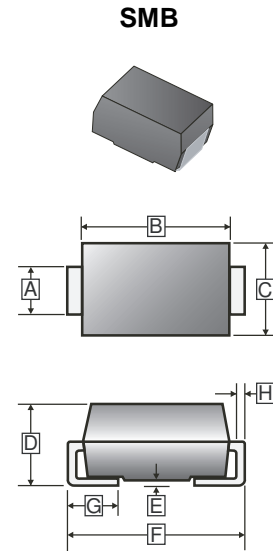
- Low Profile Package
- Ideal for Automated Placement
- Guardring for Overvoltage Protection
- Low Power Losses, High Efficiency
- High Forward Surge Capability
- Meets MSL level 1, per J-STD-020, LF Maximum Peak of 260°C

MECHANICAL DATA

- Case: SMB
Molding Compound Meets UL 94 V-0 Flammability Rating
- Terminals: Tin Plated Leads, Solderable per J-STD-002 and JESD22-B102
- Polarity: Cathode Line Denotes the Cathode End

PACKAGE INFORMATION

Package	MPQ	Leader Size
SMB	3K	13 inch



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	1.85	2.20	E	-	0.25
B	4.00	4.85	F	5.05	5.59
C	3.25	3.94	G	0.75	1.55
D	1.90	2.61	H	0.15	0.31

ORDER INFORMATION

Part Number	Type
SK5100B-C	Lead (Pb)-free and Halogen-free

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Average Rectified Output Current	I_O	5	A
Surge(Non-repetitive)Forward Current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	100	A
Maximum Instantaneous Forward Voltage Drop Per Diode @ $I_F=5A$	V_F	0.7	V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $V_R=V_{RRM}$	$T_A=25^\circ\text{C}$	0.1	mA
	$T_A=100^\circ\text{C}$	20	
Thermal Resistance from Junction-Ambient ¹	$R_{\theta JA}$	65	°C/W
Thermal Resistance from Junction-Case ¹	$R_{\theta JC}$	15	
Thermal Resistance from Junction-Lead ¹	$R_{\theta JL}$	16	
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55~150	°C

Note:

1. Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3"(8mm x 8mm) copper pad areas.

CHARACTERISTIC CURVES

FIG1: I_o -TL Curve

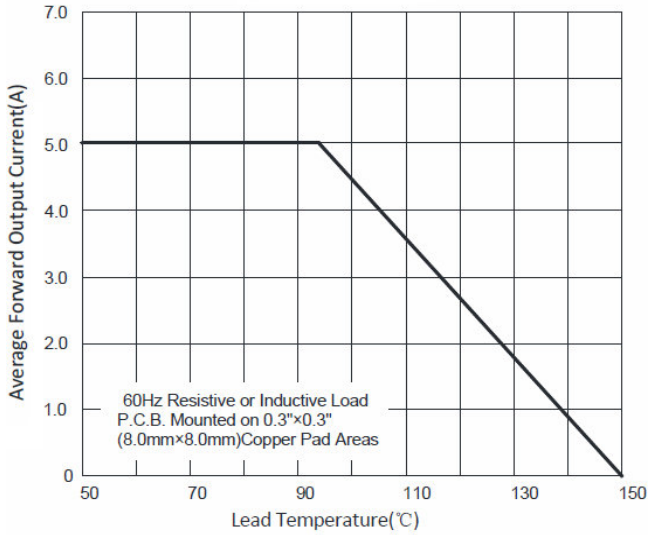


FIG2: Surge Forward Current Capability

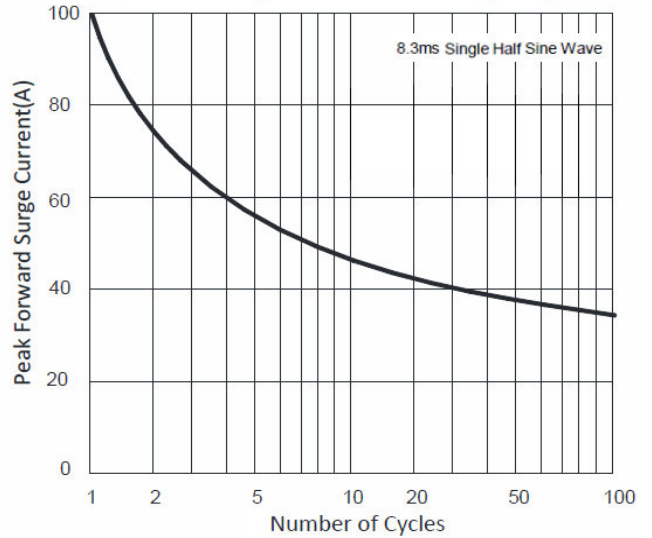


FIG3: Forward Voltage

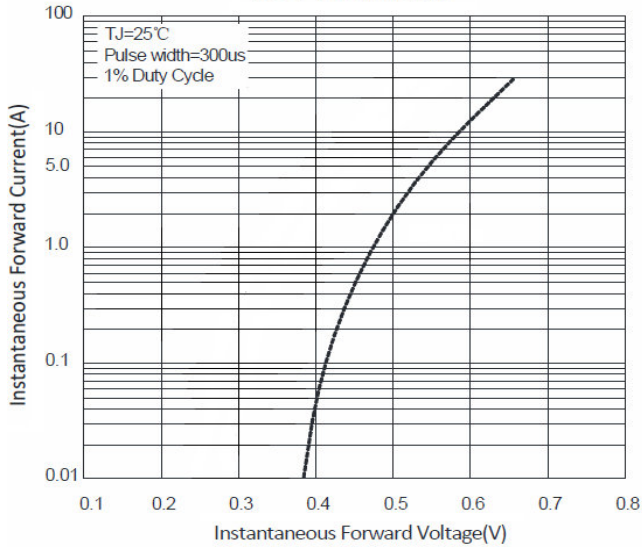


FIG4: Typical Reverse Characteristics

